增 益 实 业

零 件 承 认 书

SPECIFICATION FOR APPROVAL

客户名称: 001

增益型号： ZESMB302540

规格描述： 贴片磁珠 302540-32Ω@100MHz

日　　期: 2024/6/11

版　　本: A

增益签核:

制订	审核	核准
夏琳		李万

客户签核:

工程	审核	核准

东莞市增益实业有限公司
地址：东莞市塘厦镇林村塘厦大道北552号
电话：0769-87321000
传真：0769-87891229

物料类型：	贴片磁珠
日　　期:	2024/6/11
版　　本:	A

图面规格变更履历表

客户		立创	料号		品名	
客户版本	增益版本	变更内容	日期	制定	审核	核准
	A	初版	2024/6/11	张翔	刘业明	柯文学

东莞市增益实业有限公司
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电话：0769-87321000
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物料类型：	贴片磁珠
日　期:	2021/12/2
版　本:	A

Ⅰ. SCOPE：

This specification applies to the Pb Free Ferrite Chip Beads for

ZESMB302540

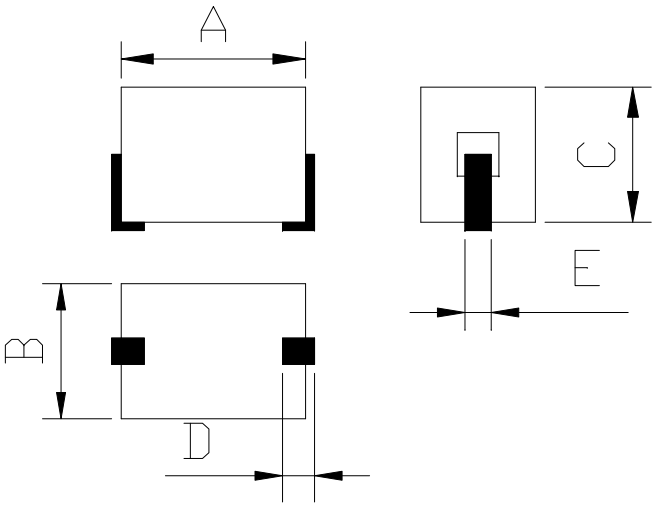
PRODUCT INDENTIFICATION

ZESMB	302540
①	②

① Product Code

② Dimensions Code

(1) SHAPES AND DIMENSIONS



A: 4.05±0.20 mm
B: 3.00±0.20 mm
C: 2.50±0.20 mm
D: 1.40±0.50 mm
E: 1.26±0.20 mm

(2) ELECTRICAL SPECIFICATIONS

SEE TABLE 1

TEST INSTRUMENTS

Z : HP 4291B IMPEDANCE ANALYER (or equivalent)

RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Temperature rise ..... ＋40℃ Max.

(3)-2 Ambient temperature ..... ＋60℃ Max.

(3)-3 Operate temperature range ..... －40℃～＋105℃

(Including self temp. rise)

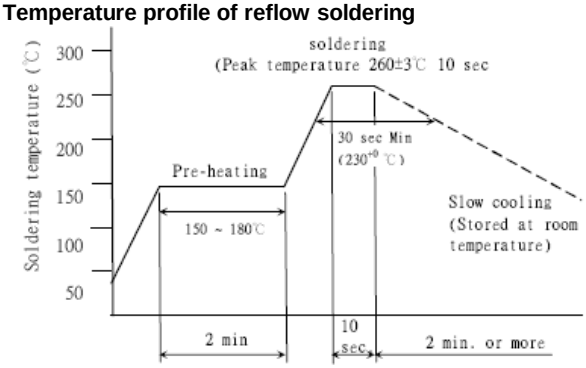
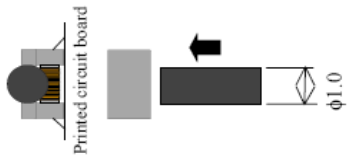
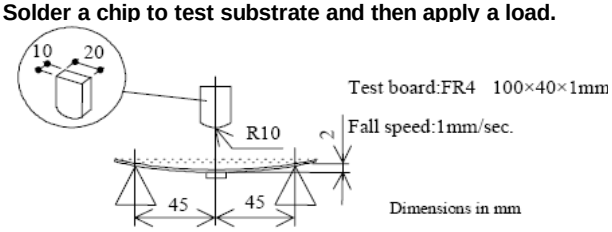
(3)-4 Storage temperature range ..... －40℃～＋105℃

TABLE 1

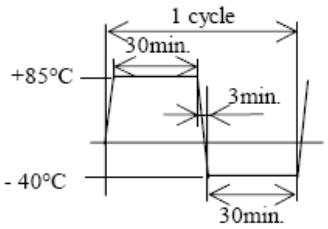
PT/NO.	IMPEDANCE (Ω)		DCR(mΩ) Max.
	At 25MHz/0.5V	At 100MHz/0.5V	
ZESMB302540	15 min	32 min	0.6

(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Solder ability	The product shall be connected to the test circuit board by the fillet (the height is 0.2mm).	Apply cream solder to the printed circuit board . Refer to clause 8 for Reflow profile.
Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Temperature profile of reflow soldering  The specimen shall be passed through the reflow oven with the condition shown in the above pro-file for 1 time. The specimen shall be stored at standard atmosph-eric conditions for 1 hour, after which the measu-rement shall be made.
Terminal strength	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate , and then laterally apply a load 9.8N in the arrow direction. 
Strength on PC board bending	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate and then apply a load. 
High temperature resistance	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. not damaged.	After the samples shall be soldered onto the test circuit board,the test shall be done. Measurement : After placing for 24 hours min. Temperature : +85±2℃ Applied current : Rated current Testing time : 500±12 hours

MECHANICAL

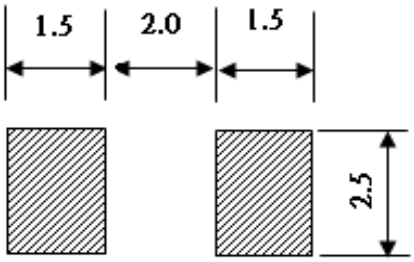
TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity resistance	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board,the test shall be done. Measurement : After placing for 24 hours min. Temperature : +60±2℃ , Humidity : 90 to 95 %RH Applied voltage : Rated voltage Applied current : Rated current Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	 Testing time : 100 cycle
Low temperature storage	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board,the test shall be done. Measurement : After placing for 24 hours min. Temperature : -40±2℃ Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board,the test shall be done. Frequency : 10 to 55 Hz Amplitude : 1.52 mm Dimension and times : X ,Y and Z directions for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of 130～150℃ and after it has been immersed to a depth 0.5mm below for 3±0.2 seconds fully in molten solder M705 with a temperature of 245±2℃. shall be couered with new solder smoothly when the sample is taken out of the solder bath.

(5) LAND DIMENSION (Ref.)

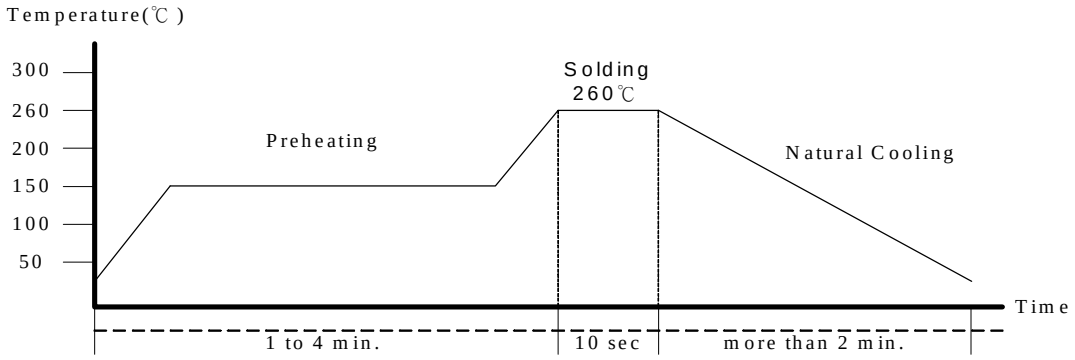
PCB: GLASS EPOXY t＝1.6mm

(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) unit：mm

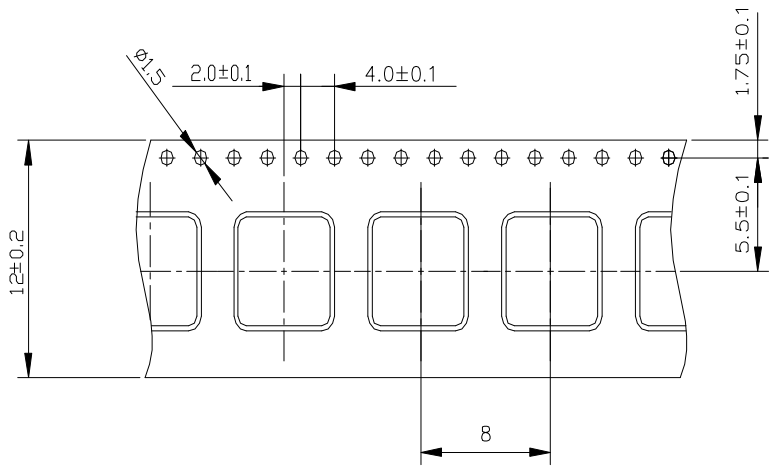


(5)-2 FLOW SOLDERING

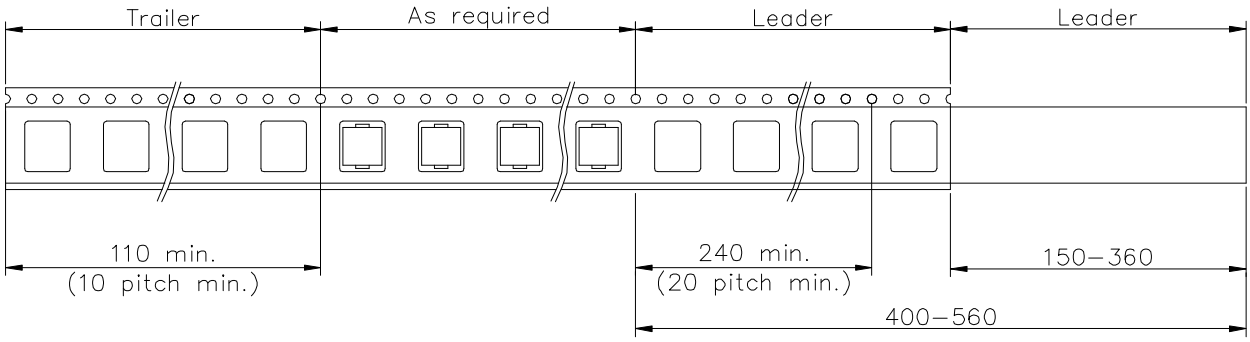


(6) PACKAGING

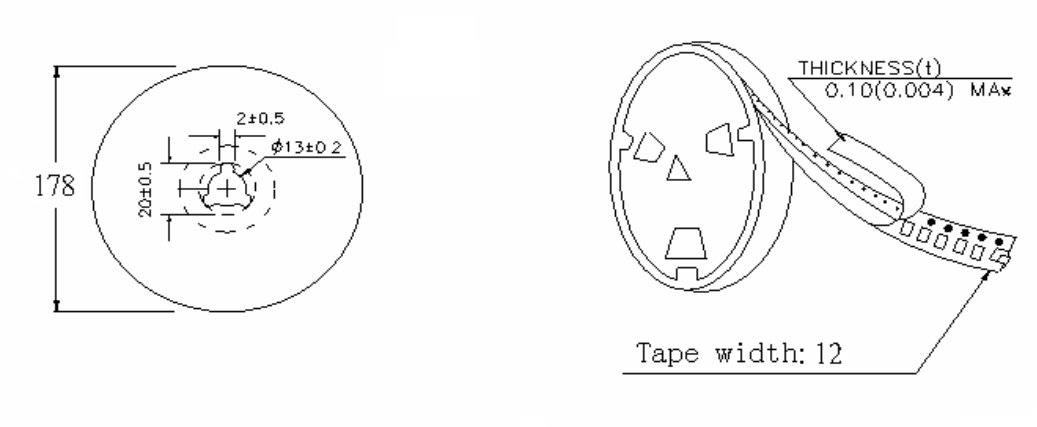
(6)-1 CARRIER TAPE DIMENSIONS (mm)



(6)-2 TAPING DIMENSIONS (mm)



(6)-3 REEL DIMENSIONS (mm)



(6)-3 QUANTITY

500pcs/Reel

TYPICAL ELECTRICAT CHARACTERISTICS